



# 100% Material Declaration Data Sheet for 7 Series FF676

PK802 (v1.0) May 19, 2016

**Average Weight: 7.8820 g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.388303</b>	<b>4.926</b>
	Silicon (Si)	7440-21-3	100.00	Basis	0.388303	
<b>Solder Bump</b>					<b>0.018136</b>	<b>0.230</b>
	Tin (Sn)	7440-31-5	63.00	Basis	0.011426	
	Lead (Pb)	7439-92-1	37.00	Basis	0.006710	
<b>Solder Paste</b>					<b>0.005400</b>	<b>0.069</b>
	Tin (Sn)	7440-31-5	96.50	Metal	0.005211	
	Silver (Ag)	7440-22-4	3.00	Metal	0.000162	
	Copper (Cu)	7440-50-8	0.50	Metal	0.000027	
<b>Capacitor 1</b>					<b>0.021600</b>	<b>0.274</b>
	Ceramic (BaTiO3 type)	12047-27-7	70.60	Ceramic	0.015250	
	Nickel (Ni)	7440-02-0	6.70	Inner electrode	0.001447	
	Copper (Cu)	7440-50-8	20.10	Outer electrode	0.004342	
	Nickel (Ni)	7440-02-0	0.80	Plating1	0.000173	
	Tin (Sn)	7440-31-5	1.80	Plating2	0.000389	
<b>Capacitor 2</b>					<b>0.003800</b>	<b>0.048</b>
	Ceramic (BaTiO3 type)	12047-27-7	61.70	Ceramic	0.002345	
	Nickel (Ni)	7440-02-0	4.89	Inner electrode	0.000186	
	Indium Tin Oxide	50926-11-9	18.30	Outer electrode	0.000695	
	Copper (Cu)	7440-50-8	13.40	Outer electrode	0.000509	
	Nickel (Ni)	7440-02-0	0.49	Plating1	0.000019	
	Tin (Sn)	7440-31-5	1.22	Plating2	0.000046	
<b>Capacitor 3</b>					<b>0.001200</b>	<b>0.015</b>
	Ceramic (BaTiO3 type)	12047-27-7	66.00	Ceramic	0.000792	
	Nickel (Ni)	7440-02-0	2.67	Inner electrode	0.000032	
	Copper (Cu)	7440-50-8	23.33	Outer electrode	0.000280	
	Nickel (Ni)	7440-02-0	2.33	Plating1	0.000028	
	Tin (Sn)	7440-31-5	5.67	Plating2	0.000068	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Capacitor 4</b>					<b>0.007360</b>	<b>0.093</b>
	Ceramic (BaTiO3 type)	12047-27-7	51.10	Ceramic	0.003761	
	Nickel (Ni)	7440-02-0	27.00	Inner electrode	0.001987	
	Copper (Cu)	7440-50-8	16.00	Outer Electrode	0.001178	
	Glass	65997-17-3	0.90		0.000066	
	Nickel (Ni)	7440-02-0	2.00	Plating1	0.000147	
	Tin (Sn)	7440-31-5	3.00	Plating2	0.000221	
<b>Underfill</b>					<b>0.049000</b>	<b>0.622</b>
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	basis	0.009800	
	Phenolic resin	trade secret	15.00	basis	0.007350	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	basis	0.002450	
	Amine type accelerator	trade secret	5.00	basis	0.002450	
	Silicon dioxide	60676-86-0	51.50	basis	0.025235	
	Carbon black	1333-86-4	1.00	basis	0.000490	
	Additives	trade secret	2.50	Additive	0.001225	
<b>Lid</b>					<b>4.615000</b>	<b>58.551</b>
	Copper (Cu)	7440-50-8	97.94	Main material	4.519931	
	Nickel (Ni)	8049-31-8	2.06	Main material	0.095069	
<b>Lid Adhesive</b>					<b>0.115000</b>	<b>1.459</b>
	Aluminium Oxide	1344-28-1	70.00	Main material	0.080500	
	Dimethyl siloxane, dimethylvinyl-terminated	68083-19-2	30.00	Main material	0.034500	
<b>Solder Ball</b>					<b>0.564707</b>	<b>7.165</b>
	Tin (Sn)	7440-31-5	63.00	Main material	0.355765	
	Lead (Pb)	7439-92-1	37.00	Main material	0.208942	
<b>Substrate</b>					<b>2.092494</b>	<b>26.548</b>
	Copper (Cu)	7440-50-8	40.50		0.847460	
	Tin (Sn)	7440-31-5	1.13		0.023645	
	Lead (Pb)	7439-92-1	0.29		0.006068	
	Silver (Ag)	7440-22-4	0.02		0.000418	
	BT Core	N/A	42.70		0.893495	
	ABF	N/A	13.17		0.275581	
	Solder Mask	N/A	2.19		0.045826	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
05/19/16	1.0	Initial Xilinx release.

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